

### 3.5x2.8 mm SMD CHIP LED LAMP

APED3528MBC

BLUE

#### Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- IDEAL FOR BACKLIGHTING.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE : 500PCS / REEL.

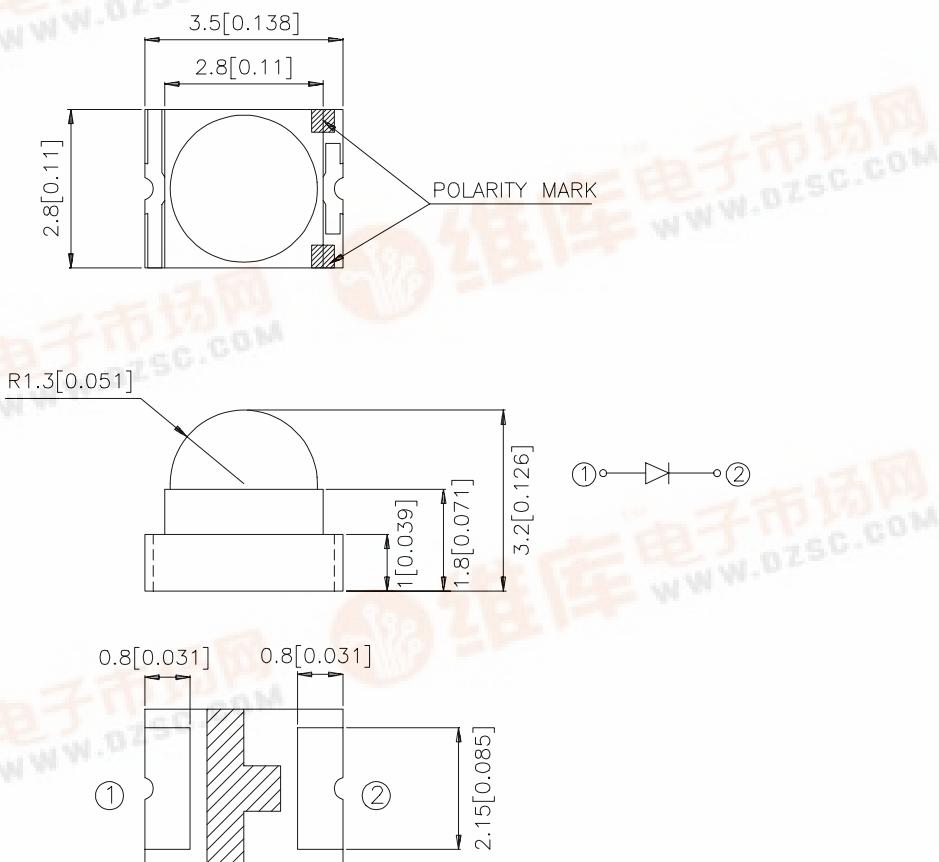
#### Description

The Blue source color devices are made with GaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

#### Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.2(0.0079")$  unless otherwise noted.
3. Specifications are subject to change without notice.

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## Selection Guide

Part No.	Dice	Lens Type	I <sub>v</sub> (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	
APED3528MBC	BLUE (GaN)	WATER CLEAR	7	40	40°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Blue	430		nm	I <sub>F</sub> =20mA
λ D	Dominate Wavelength	Blue	466		nm	I <sub>F</sub> =20mA
Δλ1/2	Spectral Line Half-width	Blue	60		nm	I <sub>F</sub> =20mA
C	Capacitance	Blue	100		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Blue	3.8	4.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Blue		10	uA	V <sub>R</sub> = 5V

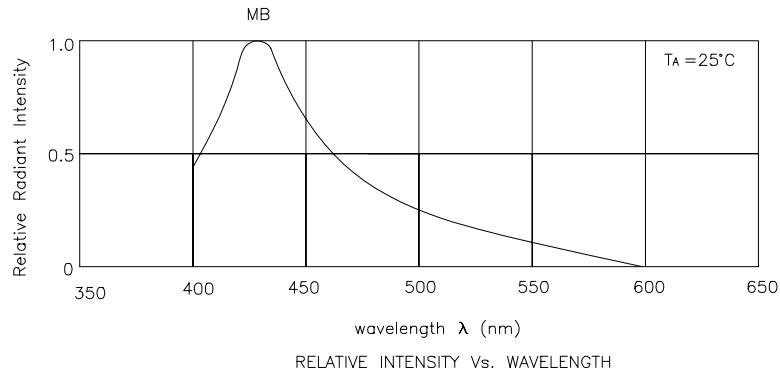
## Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Blue	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

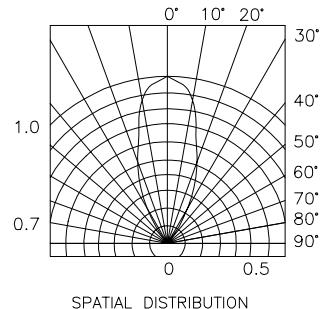
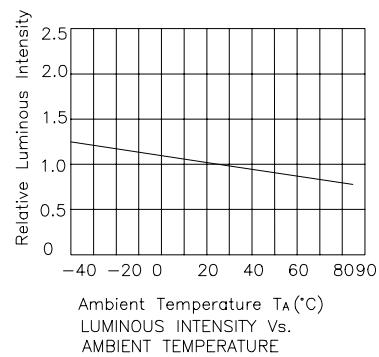
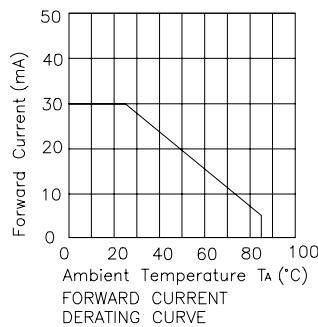
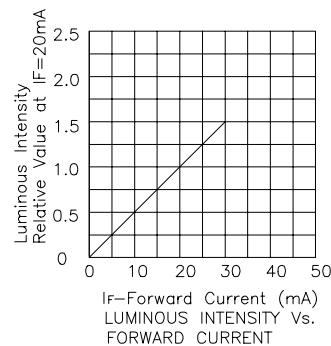
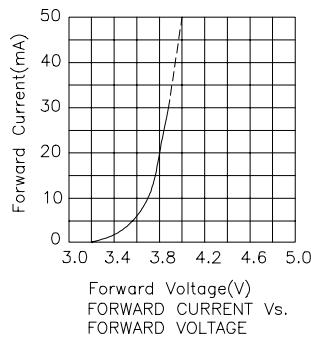
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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**Blue**

**APED3528MBC**

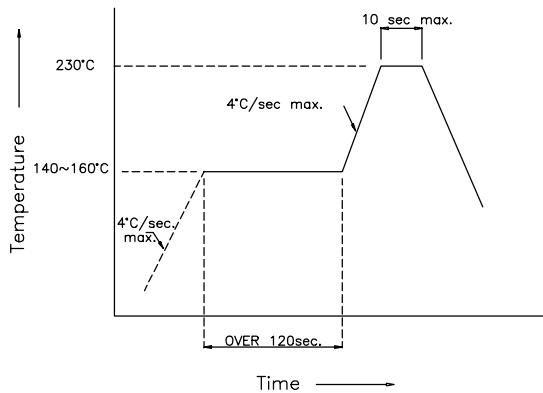


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## APED3528MBC

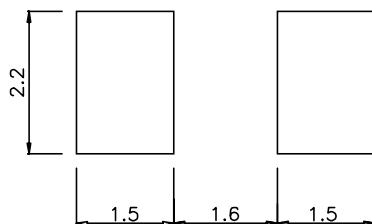
### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern

(Units : mm)



### Tape Specifications

(Units : mm)

